



Product Change Notification - KSRA-01ORPQ576

(Printer Friendly)

Date:

06 Feb 2018

Product Category:

Linear Op Amps

Notification subject:

CCB 3266 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L SOIC package at GTK assembly site

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L SOIC package at GTK assembly site

Pre Change:

Using gold (Au) bond wire, CRM-1076Dj die attach, and G600 molding compound material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 4900GC die attach, and G700 molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	GREATEK ELETRONIC INC.(GTK)	GREATEK ELETRONIC INC.(GTK)
Wire material	Au Wire	CuPdAu Wire
Die attach material	CRM-1076DJ	4900GC
Molding compound material	G600	G700
Lead frame material	A194	A194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire, 4900GC die attach, and G700 molding compound material at GTK assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

July 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2018					→	July 2018				
Workweek	05	06	07	08	09		27	28	29	30	31
Initial PCN Issue Date		X									
Qual								X			

Report Availability																					
Final PCN Issue Date														X							

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

February 06, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-01ORPQ576_Affected CPN.pdf](#)

[PCN_KSRA-01ORPQ576_Qual Plan.pdf](#)

[PCN_KSRA-01ORPQ576_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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